## Product End-of-Life Disassembly Instructions

**Product Category:** Monitors and Displays

**Marketing Name / Model**
[List multiple models if applicable.]

| HP LA2405wg Widescreen LCD Monitor | |
| Name / Model #2 | |
| Name / Model #3 | |
| Name / Model #4 | |
| Name / Model #5 | |

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

### 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>4</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>0</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>4</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>1</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>4</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
Components, parts and materials containing radioactive substances  

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 SCREW DRIVER(PHILLIPS HEAD)</td>
<td>#2</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove Stand Base From Display Head
2. Remove Rear Cover From Display Head
3. Remove Front Cover From Display Head
4. Remove Front Trim Cover From Front Cover
5. Take Screw(*4) Off From Chassis Cover & Remove Panel
6. Take Screw(x8) Off From P.C.B & Remove BKT
7. Remove Mylar From Chassis Cover
8. Take Screw(*4) Off From VESA Mount
9. Remove VESA Cover From VESA Mount BKT
10. Take Screw(*2) Off From Stand Base
11. Remove Slide Cover From Stand Base
12. Take Screw(*4) Off From Stand Base BKT
13. Remove Base Rubber(*7) From Base BKT
14. Take Screw(*6) Off From Base BKT
15. Take Screw(*4) Off From Base BKT
16. Remove Stand Rear Lower Cover From Stand Base BKT
17. Take Screw(*4) Off From Stand Base BKT

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
HP-LA2405wg Disassembly Process

- April Chiu
- Mechanical Engineer
- May-20-2009
External Electric Cables Dissecting Process

1. Remove Cable From Display Head.

2. Dissecting To Complete.
1. Turning Right or Left 45°.
2. Take Screw(*2) Off From Display Head

3. Remove Stand Base From Display Head.
Remove Stand Base From Display Head

4. Dissecting To Complete.

2. Remove Rear Cover From Display Head.
Remove Front Cover From Display Head

1. Take Screw(*4) Off From Front Cover
2. Remove Front Cover.
1. Remove Front Trim Cover From Front Cover.

2. Dissecting To Complete.
Take Screw(*4) Off From Chassis Cover & Remove Panel

1. Remove connector from Chassis cover.
2. Take Screw(x4) Off from Chassis cover & Remove Speaker Off From Chassis Cover.
3. Remove connector off from Panel.
4. Remove the panel.
Take Screw(x8) Off From P.C.B & Remove BKT (Printed Circuit Assemblies>10cm**2)

1. Take screw(*4) off from PCB.

2. Take screw(*5) off from P.C.B.

3. Remove Connector off from P.C.B
Take Screw(x8) Off From P.C.B & Remove BKT (Printed Circuit Assemblies>10cm**2)

INTERFACE BOARD

FUNCTION KEY BOARD

POWER BOARD

USB COVER

PANEL

CHASSIS COVER

Dissecting to complete.
Remove Mylar From Chassis Cover
LCD PANEL EXPLODE

Remove PCB Cover

Disassemble top chassis and Separate Glass from BLU
Disassemble lamp wire from guide of mold frame and bottom chassis
Disassemble the mold frame from the bottom chassis.
Separate LGP from bottom chassis.
LCD PANEL EXPLODE

- Remove the tape.

- Separate Bottom chassis and LGP to pull out lamp assy.

※ Pull out the lamp assy from backlight
Electrolytic Capacitors Over 25mm High & Diameter Dissecting Process

1. Heats Up, Dissolved Tin Lead.
2. Takes Down The Capacitor.
3. Dissecting To Complete.
(Next Page Have Description)
Take Screw(*4) Off From VESA Mount

1. Take screw(*4) off from VESA Mount.

2. Remove VESA Mount From Stand Base.
Remove VESA Cover From VESA Mount BKT

1. Use tool, Let the rubber melt, And Remove VESA Cover.
1. Take Screw(*2) Off From Stand Base.

2. Remove Stand Rear Upper Cover From Stand Base.
Remove Slide Cover From Stand Base
1. Take screw(*4) off from Stand Base BKT.

2. Both Hands Downwardly.

3. Remove Stand Front Upper Cover From Stand Base.
Remove Base Rubber(*7) From Base BKT
1. Take Screw(*6) Off From Base BKT.

2. Take Screw(*2) Off From Base BKT.
Take Screw(*6) Off From Base BKT

3. Dissecting To Complete.
Take Screw(*4) Off From Base BKT

1. Take screw(*4) off from Base BKT.

2. Dissecting To Complete.
Remove Stand Rear Lower Cover From Stand Base BKT
Take Screw(*4) Off From Stand Base BKT

1. Take screw(*4) off from Stand Base BKT.

2. Downwardly To Rotate.

3. Remove Stand Front Lower Cover from Stand Base BKT.

4. Dissecting To Complete.